

#13
PATENT
9/3/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

5 Applicant: Kuo-Ming Chen
Examiner: Nguyen, Dilinh P
Filing Date: 05/21/2002 Art Unit: 2814
App. No.: 10/063,880 Docket No.: NAUP0481USA

10 Title: SOLDER PADS FOR IMPROVING RELIABILITY OF A
PACKAGE

To: Commissioner for Patents
P.O. Box 1450
15 Alexandria VA 22313-1450

Subject: Response to the Office action dated 06/04/2003

Dear Sir or Madame:

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INTRODUCTORY COMMENTS

25 In response to the Office action identified above,
the above-identified application is to be amended as
indicated in the following sections. Consideration of
all amendments is politely requested.

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